

Название: Мини-платформа отопления

Модель: ВВ-215А

Темп. Диапазон: 160~250°C

СЗ: 90,4 г

Рабочая область: 20\*18,5 мм

Размер продукта: 70,5x76,7x21,6 мм

Применение: Подходит для 99% чипов на рынке, универсален для удаления клея и олова с различных типов iPhone, Huawei и других процессоров мобильных телефонов.

Type-C USB

# Mini Heating Platform

160°C~250°C Adjustable

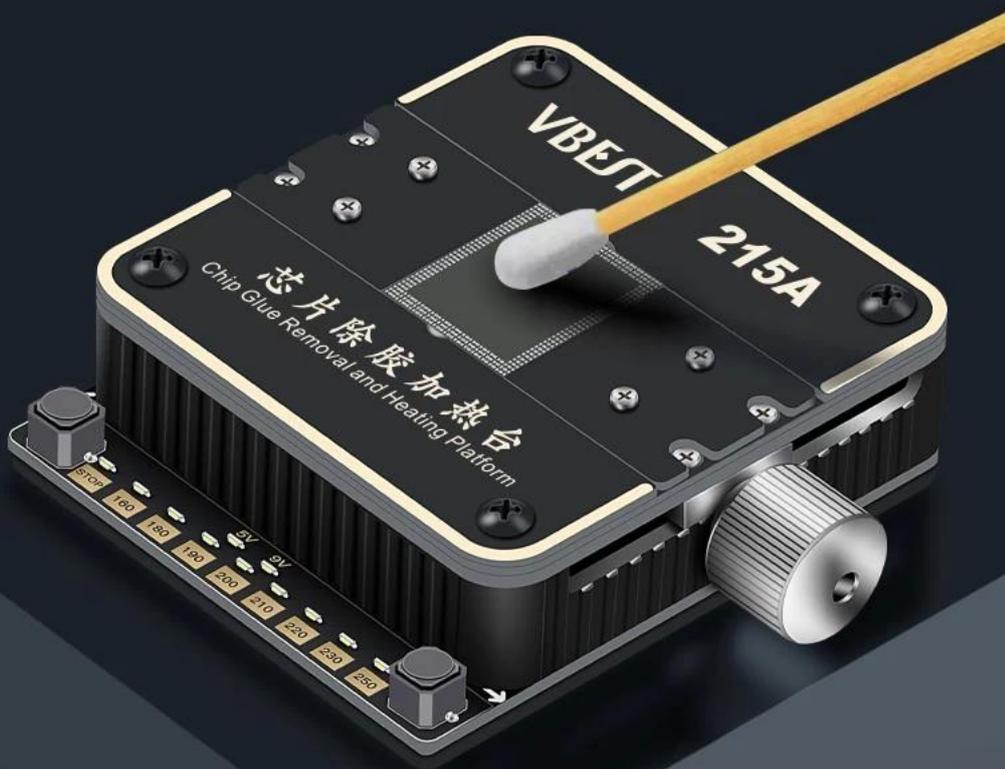
No need for heat gun or soldering iron heating, no need for soldering wick  
No damage to solder pads and paint



# No need for Soldering Wick



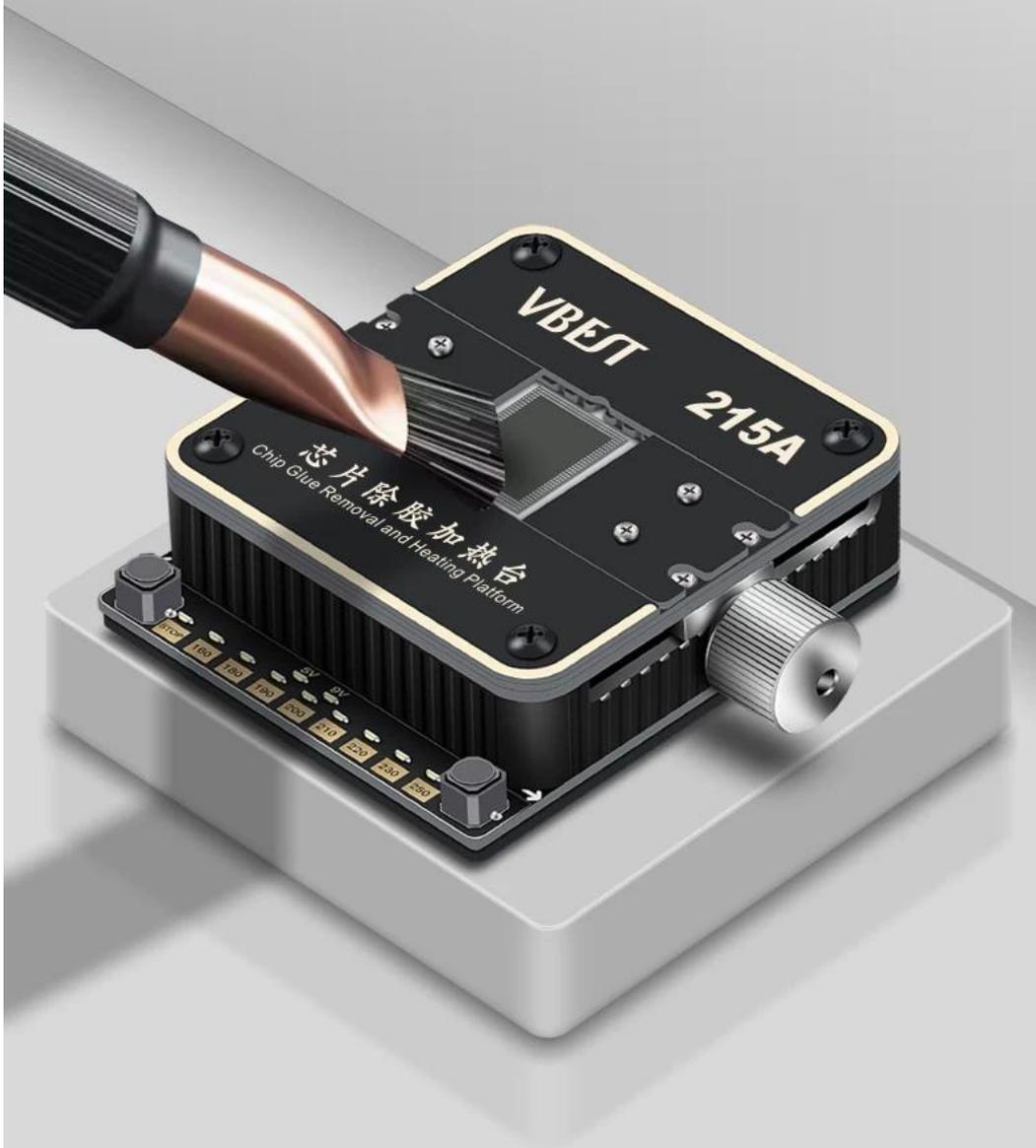
After heating to the set temperature, use a cotton swab to clean up the residual tin. No damage to the solder pad paint, no need for soldering wick wiping to wear out the chip



## Heating to remove tin



Turn on the heating platform and heating to the preset temperature, you can use a brush or cotton swab to remove residual tin without soldering wick. Gently wipe to remove tin and glue easily.



160°C~250°C

## Constant Temperature Heating



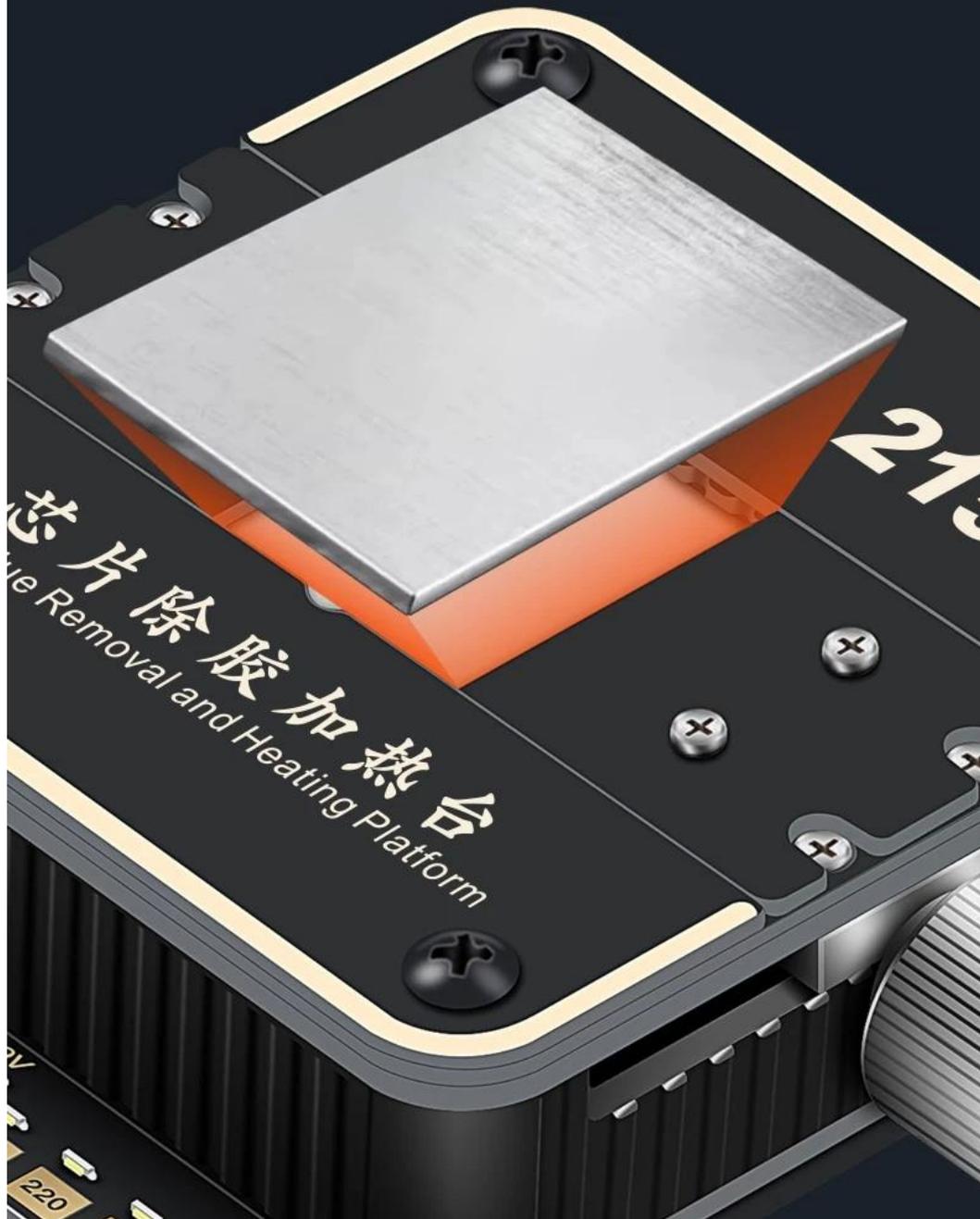
During heating operation, the temperature can be adjusted between 160~250 °C  
Effectively prevent chip burnout caused by high temperature or improper adjustment



# Low Voltage Heating Plate



Fast heating, no leakage, anti-static, safer heating  
Built in professional tuning curve, no need to worry about  
chip damage caused by thermal stress



## Flexible hidden screw rod



Hidden screw rod, flexible and clever, extendable  
and fixed clamping the chips  
Prevent residue from falling into the screw,  
making it more durable



# Uniform Heating



No need for heat gun heating, it is safer to scrape glue  
at a temperature 100 °C lower than the heat gun  
No need to repeatedly scrape with a soldering iron,  
no damage to the solder pads



**Temperature adjustable**

**160~250°C**

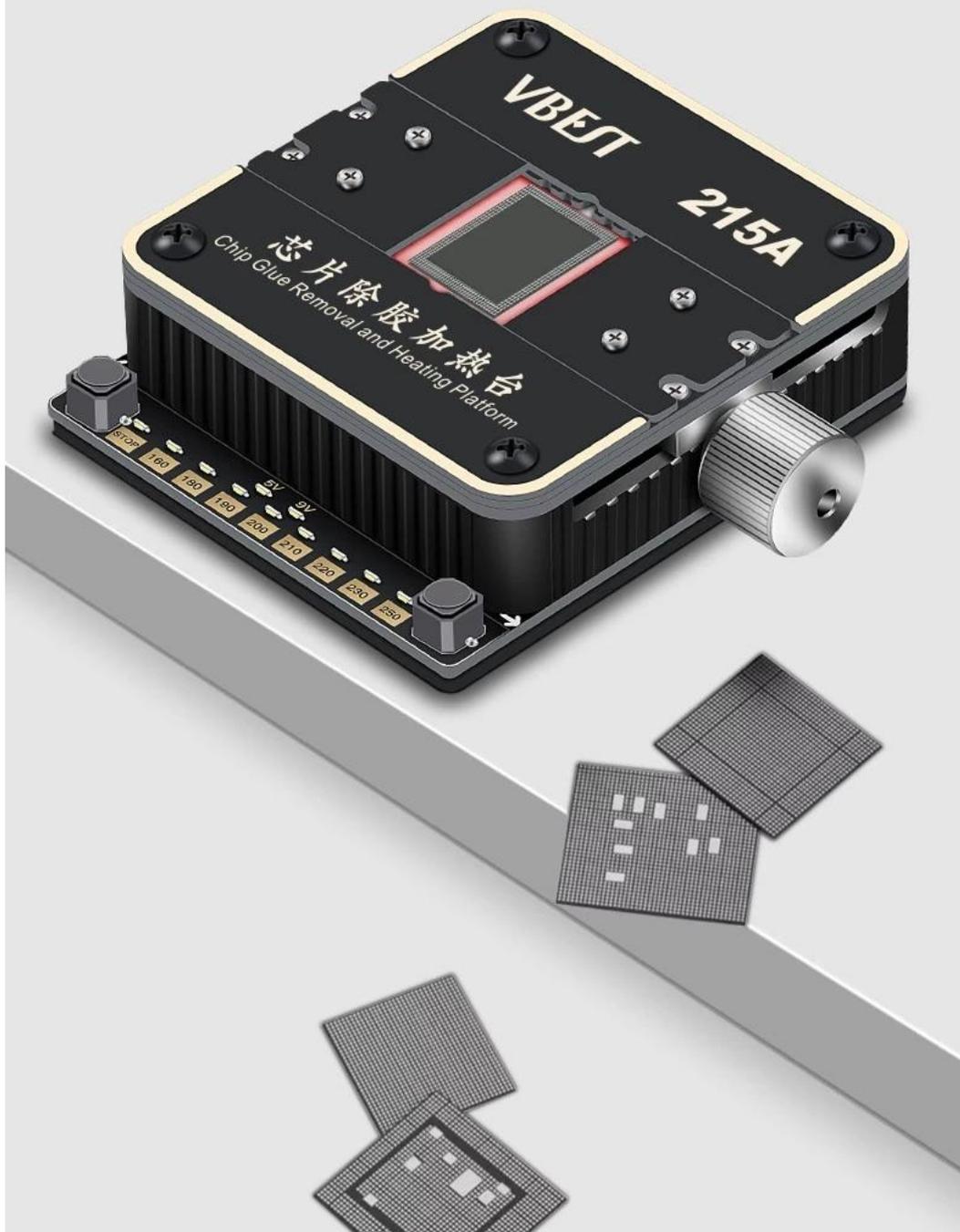


# Suitable for 99% of chips

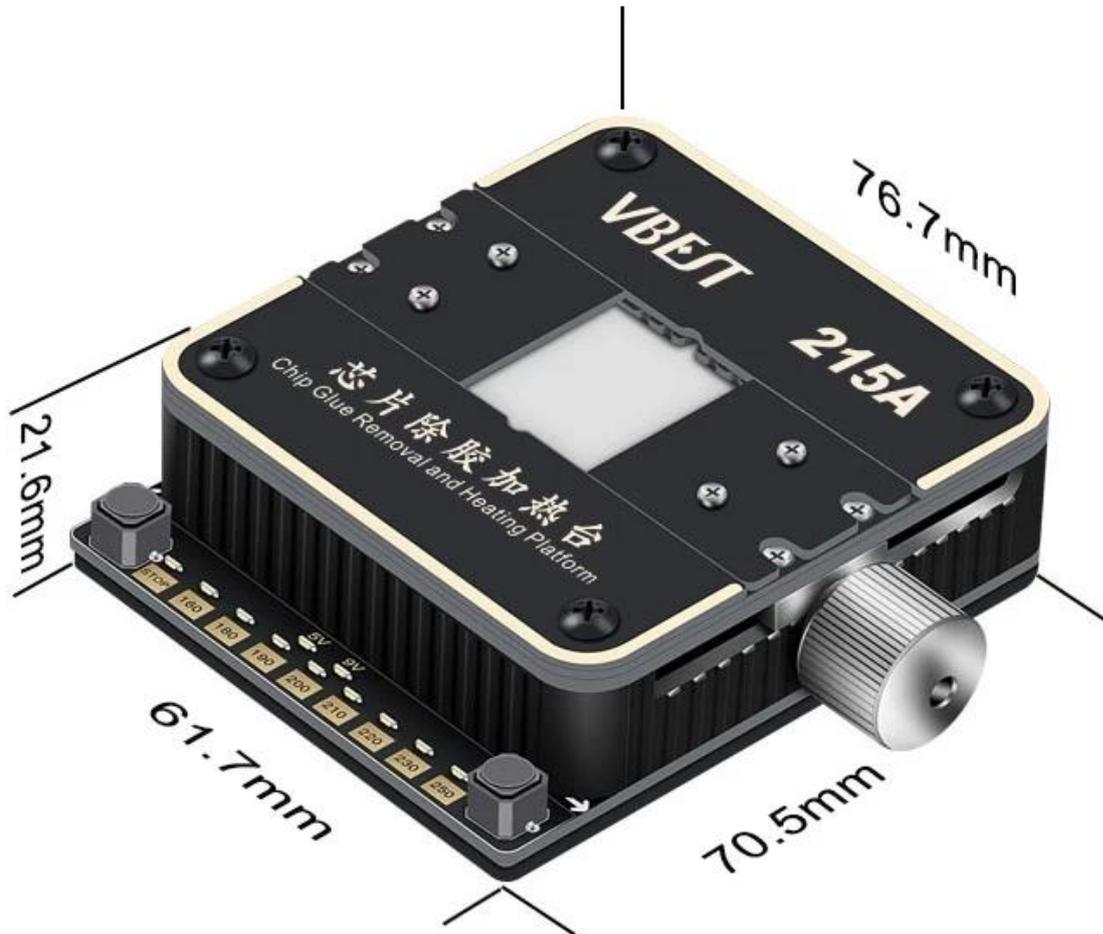


Work area: 20mm×18.5mm (Max)

Support multi generation iPh, Huawei phone CPU chips  
and hard drives



# Parameter



## Name

Mini Heating Platform

## Model

VB-215A

## Temp. Range

160~250°C

## N. W.

90.4g

## Work area

20×18.5mm

## Product Size

70.5×76.7×21.6mm

## Application

Suitable for 99% of chips on the market, universal for removing glue and tin from various types of iPhones, Huawei and other mobile phone CPU

\* The above dimensions are measured manually and may have about 1-2mm error